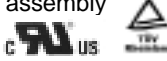




**LP-USM035**

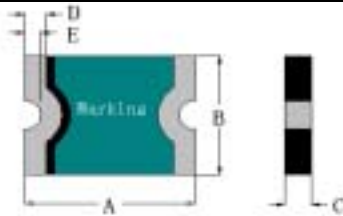
**Features**

- Smaller size of 1210
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV

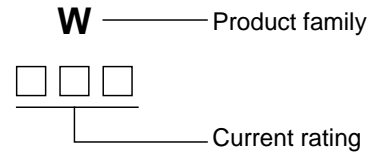


**Product Dimensions (mm)**

Part number	A	B	C	D	E
	Max	Max	Max	Max	Min.
LP-USM035	3.43	2.80	0.85	0.60	0.20



**Part Marking System**

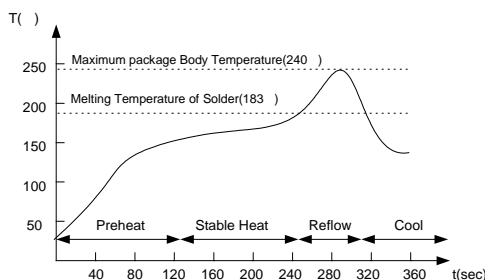
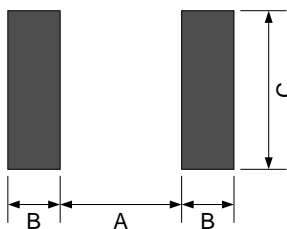


**Electrical Characteristics**

Part number	$I_H$ (A)	$I_T$ (A)	$V_{max}$ (V)	$I_{max}$ (A)	$T_{trip}$ Current(A) Time(S)	$Pd_{typ}$ (W)	$R_{min}$ ( )	$R_{1max}$ ( )
LP-USM035	0.35	0.70	6	40	8.0 0.20		0.32	1.30

$I_H$ =Hold current: maximum current at which the device will not trip at 25 still air.  
 $I_T$ =Trip current: minimum current at which the device will always trip at 25 still air.  
 $V_{max}$ =Maximum voltage device can withstand without damage at rated current.  
 $I_{max}$ =Maximum fault current device can withstand without damage at rated voltage.  
 $T_{trip}$ =Maximum time to trip(s) at assigned current.  
 $Pd_{typ}$ =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.  
 $R_{min}$ =Minimum device resistance at 25 prior to tripping.  
 $R_{1max}$ =Maximum device resistance measured in the nontripped state 1 hour post reflow.

**Solder Reflow Recommendations**



**Solder Pad Layouts**

Part number	A (mm)	B (mm)	C (mm)
LP-USM035	2.00	1.00	2.50

\* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.  
 \* Devices can be cleaned using standard industry methods and solvents.

**Notes:**

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

**Package Information**

Tape & Reel: 2000pcs per reel.